

Title (en)

APPARATUS FOR A THIN FILM MANUFACTURING

Title (de)

VORRICHTUNG FÜR DÜNNFILMHERSTELLUNG

Title (fr)

APPAREIL DESTINE A LA FABRICATION D'UNE COUCHE MINCE

Publication

EP 0728224 A4 19971022 (EN)

Application

EP 95931033 A 19950829

Priority

- KR 19940022171 A 19940903
- US 9511039 W 19950829

Abstract (en)

[origin: WO9607769A1] An apparatus for manufacturing a thin film for a semiconductor device which includes a vacuum chamber (22), a heater block (23) installed in the vacuum chamber (22) for heating the wafer (200), a sputtering source (24) installed above the heater block (23), a clamp (26) for clamping the wafer (200) installed on the heater block (23) against the heater block (23), and a gas supply means (40) for directly supplying gas to two specific sites in the vacuum chamber (22) which comprises a first gas supply (41) for supplying a first gas proximate the top of the wafer (200) from an opening (44) formed along the exterior surface of the sputtering source (24), and a second gas supply (45) positioned to supply a second gas to the top of the wafer (200). The present invention reduces the formation of undesirable particles in the vacuum chamber (22) thereby improving the characteristics of the deposited film and production efficiency.

IPC 1-7

C23C 14/34; C23C 14/50

IPC 8 full level

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- No further relevant documents disclosed
- See references of WO 9607769A1

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